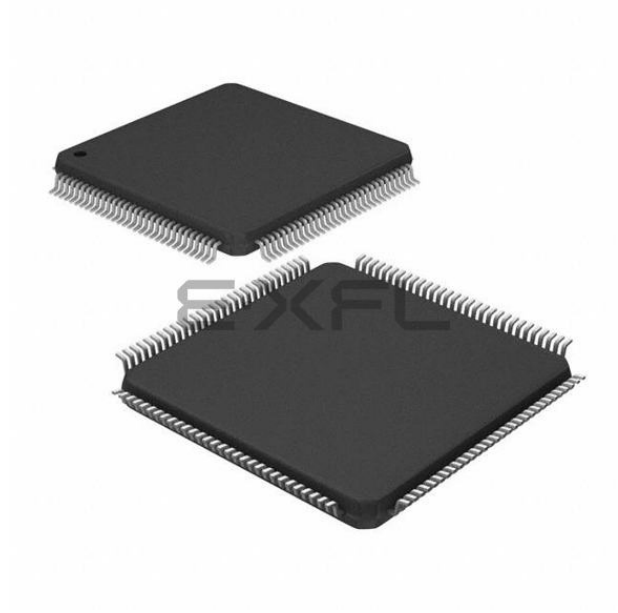


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	160MHz
Connectivity	CANbus, CSIO, EBI/EMI, I²C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	100
Program Memory Size	544KB (544K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2h46g0agv20000

- Various error detect functions available (parity errors, framing errors, and overrun errors)

- CSIO
  - Full-duplex double buffer
  - Built-in dedicated baud rate generator
  - Overrun error detect function available
  - Serial chip select function (ch.6 and ch.7 only)
  - Supports high-speed SPI (ch.4 and ch.6 only)
  - Data length 5 to 16-bit

- LIN
  - LIN protocol Rev.2.1 supported
  - Full-duplex double buffer
  - Master/Slave mode supported
  - LIN break field generation (can change to 13 to 16-bit length)
  - LIN break delimiter generation (can change to 1 to 4-bit length)
  - Various error detect functions available (parity errors, framing errors, and overrun errors)

- I^2C
  - Standard mode (Max 100 kbps) / High-speed mode (Max 400 kbps) supported
  - Fast mode Plus (Fm+) (Max 1000 kbps, only for ch.3=ch.A and ch.7=ch.B) supported

DMA Controller (8 channels)

DMA Controller has an independent bus for CPU, so CPU and DMA Controller can process simultaneously.

- 8 independently configured and operated channels
- Transfer can be started by software or request from the built-in peripherals
- Transfer address area: 32-bit (4 Gbytes)
- Transfer mode: Block transfer/Burst transfer/Demand transfer
- Transfer data type: bytes/half-word/word
- Transfer block count: 1 to 16
- Number of transfers: 1 to 65536

DSTC (Descriptor System data Transfer Controller) (256 channels)

The DSTC can transfer data at high-speed without going via the CPU. The DSTC adopts the Descriptor system and, following the specified contents of the Descriptor which has already been constructed on the memory, can access directly the memory /peripheral device and performs the data transfer operation.

It supports the software activation, the hardware activation and the chain activation functions.

A/D Converter (Max 24 channels) [12-bit A/D Converter]

- Successive Approximation type
- Built-in 3 units
- Conversion time: 0.5 µs @ 5 V
- Priority conversion available (priority at 2 levels)
- Scanning conversion mode
- Built-in FIFO for conversion data storage (for SCAN conversion: 16 steps, for Priority conversion: 4 steps)

DA Converter (Max 2 channels)

- R-2R type
- 12-bit resolution

Base Timer (Max 8 channels)

Operation mode is selectable from the followings for each channel.

- 16-bit PWM timer
- 16-bit PPG timer
- 16-/32-bit reload timer
- 16-/32-bit PWC timer
- Event counter mode (external clock mode)

General Purpose I/O Port

This series can use its pins as general purpose I/O ports when they are not used for external bus or peripherals. Moreover, the port relocate function is built in. It can set which I/O port the peripheral function can be allocated.

- Capable of pull-up control per pin
- Capable of reading pin level directly
- Built-in the port relocate function
- Up to 100 high-speed general-purpose I/O ports @ 120 pin Package
- Some pin is 5 V tolerant I/O.

See 4. Pin Description and 5. I/O Circuit Type for the corresponding pins.

Multi-function Timer (Max 3 units)

The Multi-function timer is composed of the following blocks.

Minimum resolution: 6.25 ns

- 16-bit free-run timer × 3ch./unit
- Input capture × 4ch./unit
- Output compare × 6ch./unit
- A/D activation compare × 6ch./unit
- Waveform generator × 3ch./unit
- 16-bit PPG timer × 3ch./unit

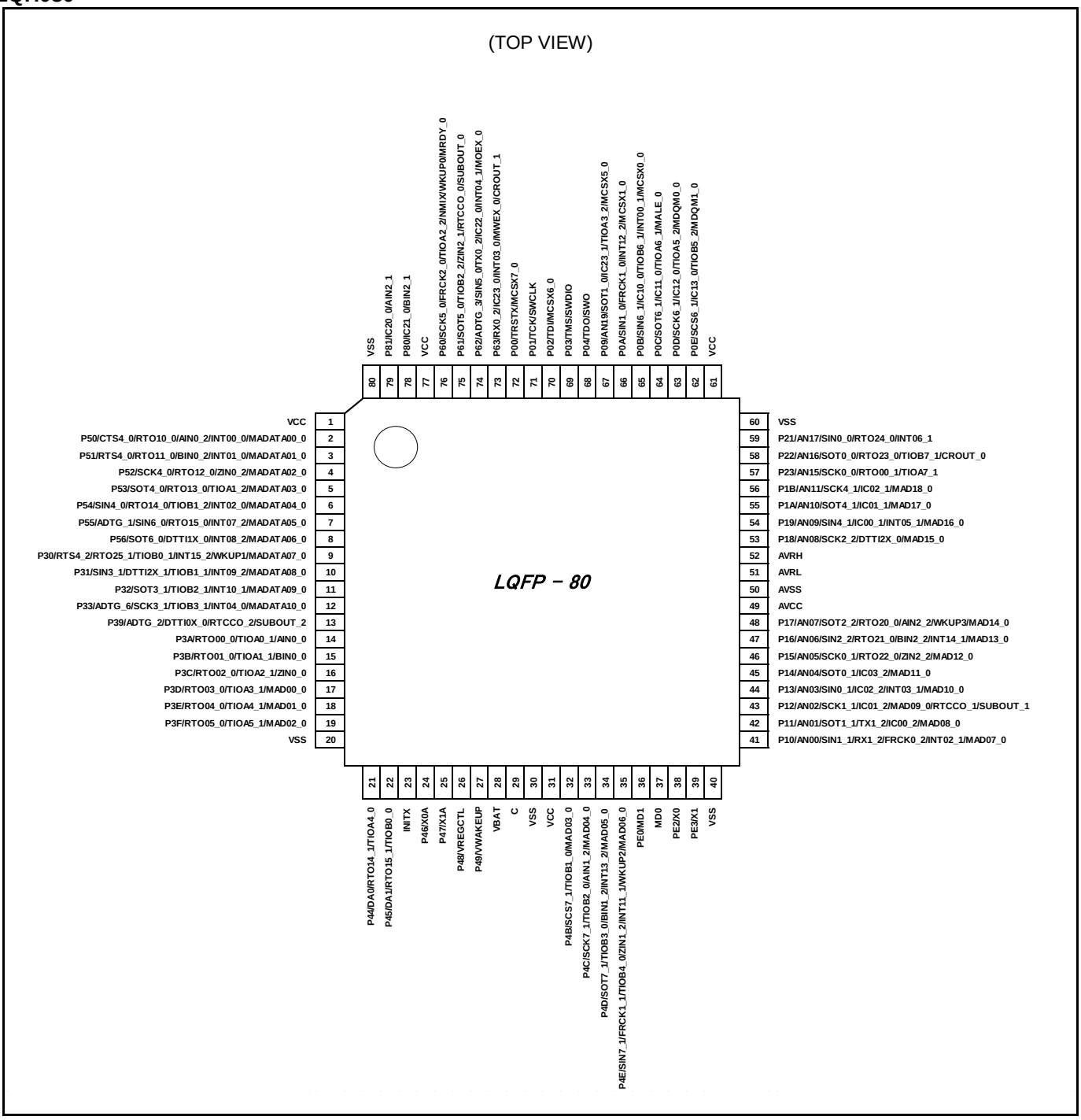
The following function can be used to achieve the motor control.

- PWM signal output function
- DC chopper waveform output function
- Dead time function
- Input capture function

Table of Contents

3. Pin Assignment

LQH080



Note:

- *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

Pin Function	Pin Name	Function Description	Pin No			
			LQFP 120	LQFP 100	LQFP 80	FBGA 121
Quadrature Position/ Revolution Counter 1	AIN1_0	QPRC ch.1 AIN input pin	10	-	-	F5
	AIN1_1		89	74	-	B11
	AIN1_2		48	43	33	J7
	BIN1_0	QPRC ch.1 BIN input pin	11	-	-	F6
	BIN1_1		88	73	-	C11
	BIN1_2		49	44	34	J8
	ZIN1_0	QPRC ch.1 ZIN input pin	12	-	-	G5
	ZIN1_1		87	72	-	C10
	ZIN1_2		50	45	35	K8
Quadrature Position/ Revolution Counter 2	AIN2_0	QPRC ch.2 AIN input pin	33	28	-	J3
	AIN2_1		119	99	79	A2
	AIN2_2		69	59	48	F9
	BIN2_0	QPRC ch.2 BIN input pin	34	29	-	J5
	BIN2_1		118	98	78	A3
	BIN2_2		68	58	47	F10
	ZIN2_0	QPRC ch.2 ZIN input pin	35	30	-	H5
	ZIN2_1		115	95	75	B3
	ZIN2_2		67	57	46	G8
Real-time clock	RTCCO_0	0.5 seconds pulse output pin of Real-time clock	115	95	75	B3
	RTCCO_1		64	54	43	H9
	RTCCO_2		23	18	13	H1
	SUBOUT_0	Sub clock output pin	115	95	75	B3
	SUBOUT_1		64	54	43	H9
	SUBOUT_2		23	18	13	H1
Low-Power Consumption Mode	WKUP0	Deep standby mode return signal input pin 0	116	96	76	B2
	WKUP1	Deep standby mode return signal input pin 1	14	9	9	E1
	WKUP2	Deep standby mode return signal input pin 2	50	45	35	K8
	WKUP3	Deep standby mode return signal input pin 3	69	59	48	F9
DAC	DA0	D/A converter ch.0 analog output pin	36	31	21	K3
	DA1	D/A converter ch.1 analog output pin	37	32	22	J4
VBAT	VREGCTL	On-board regulator control pin	41	36	26	K5
	VWAKEUP	The return signal input pin from a hibernation state	42	37	27	K6
CAN0	TX0_0	CAN interface ch.0 TX output pin	51	-	-	H6
	TX0_1		18	13	-	F1
	TX0_2		114	94	74	C3
	RX0_0	CAN interface ch.0 RX input pin	52	-	-	H7
	RX0_1		19	14	-	G1
	RX0_2		113	93	73	B4
CAN1	TX1_0	CAN interface ch.1 TX output pin	84	-	-	C9
	TX1_1		12	-	-	G5
	TX1_2		63	53	42	H10
	RX1_0	CAN interface ch.1 RX input pin	85	-	-	B10
	RX1_1		11	-	-	F6
	RX1_2		62	52	41	J10

6. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

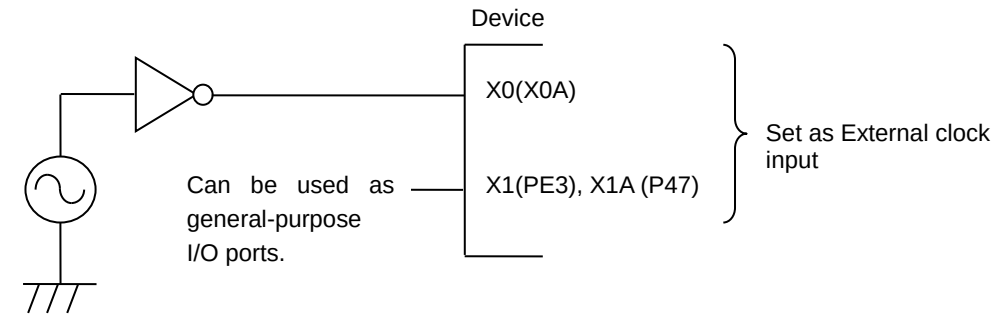
Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

Code: DS00-00004-3E

Using an External Clock

When using an external clock as an input of the main clock, set X0/X1 to the external clock input, and input the clock to X0. X1(PE3) can be used as a general-purpose I/O port.
Similarly, when using an external clock as an input of the sub clock, set X0A/X1A to the external clock input, and input the clock to X0A. X1A (P47) can be used as a general-purpose I/O port.

Example of Using an External Clock

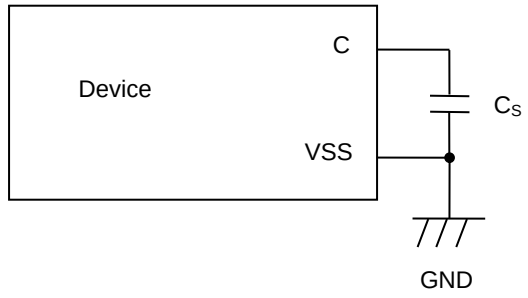


Handling when Using Multi-function Serial Pin as I²C Pin

If it is using the multi-function serial pin as I²C pins, P-ch transistor of digital output is always disabled.
However, I²C pins need to keep the electrical characteristic like other pins and not to connect to the external I²C bus system with power OFF.

C Pin

This series contains the regulator. Be sure to connect a smoothing capacitor (C_S) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor.
However, some laminated ceramic capacitors have the characteristics of capacitance variation due to thermal fluctuation (F characteristics and Y5V characteristics). Please select the capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of a capacitor.
A smoothing capacitor of about 4.7 µF would be recommended for this series.



Mode Pins (MD0)

Connect the MD pin (MD0) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, as well as the distance between the mode pins and VCC pins or VSS pins is as short as possible and the connection impedance is low, when the pins are pulled-up/down such as for switching the pin level and rewriting the Flash memory data. It is because of preventing the device erroneously switching to test mode due to noise.

Notes on Power-on

Turn power on/off in the following order or at the same time.
If not using the A/D converter and D/A converter, connect AVCC = VCC and AVSS = VSS.

Turning on: VBAT → VCC
VCC → AVCC → AVRH
Turning off: VCC → VBAT
AVRH → AVCC → VCC

Serial Communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication.
Therefore, design a printed circuit board so as to avoid noise.

Consider the case of receiving wrong data due to noise, perform error detection such as by applying a checksum of data at the end.
If an error is detected, retransmit the data.

Differences in Features among the Products with Different Memory Sizes and between Flash Products and MASK Products

The electric characteristics including power consumption, ESD, latch-up, noise characteristics, and oscillation characteristics among the products with different memory sizes and between Flash products and MASK products are different because chip layout and memory structures are different.

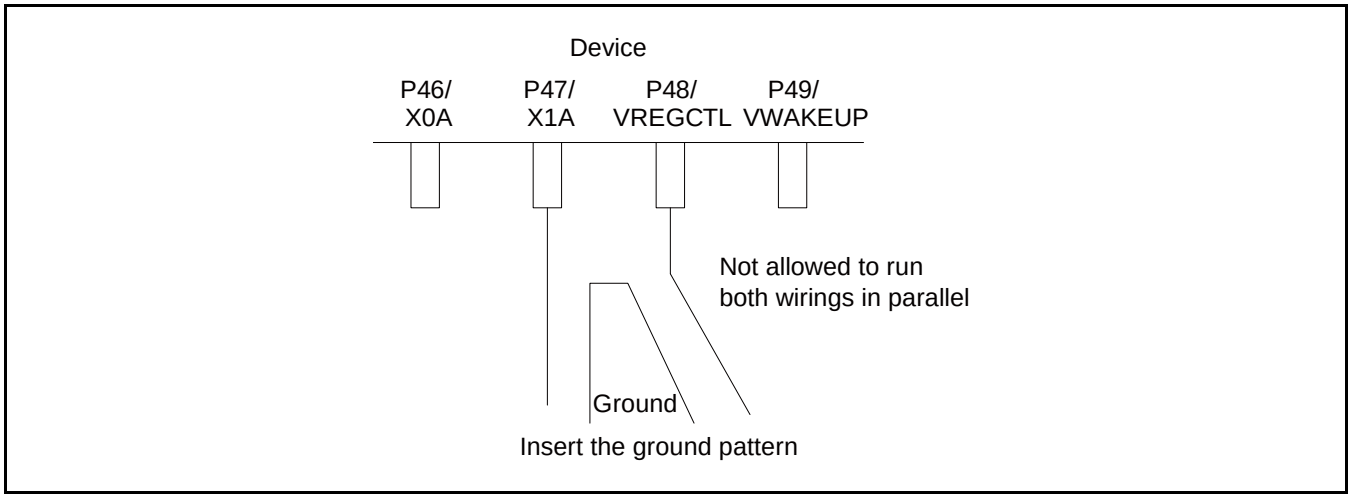
If you are switching to use a different product of the same series, please make sure to evaluate the electric characteristics.

Pull-Up Function of 5 V Tolerant I/O

Please do not input the signal more than VCC voltage at the time of Pull-Up function use of 5 V tolerant I/O.

Adjoining Wiring on Circuit Board

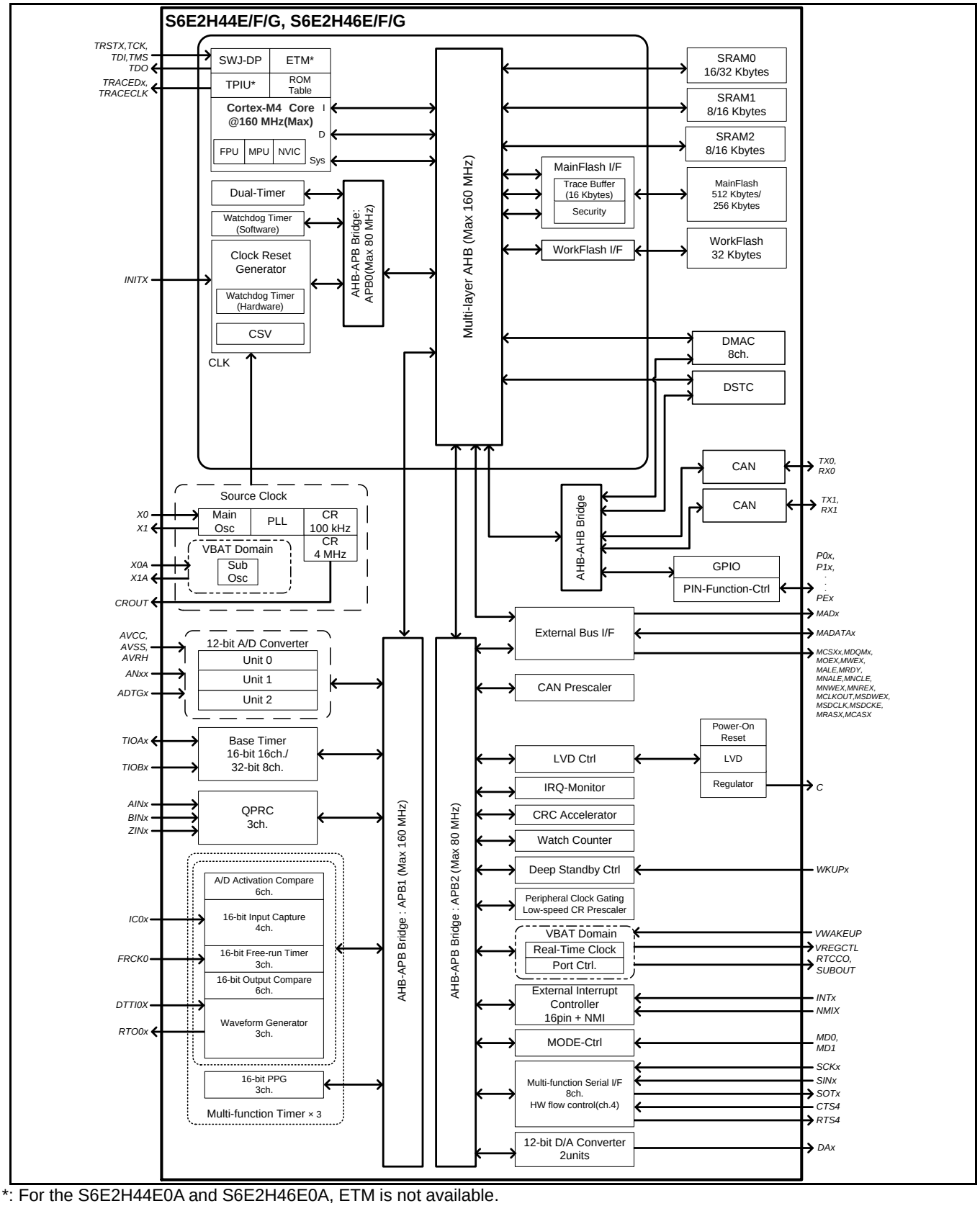
If wiring of the crystal oscillation circuit X1A adjoins and also runs in parallel with the wiring of P48/VREGCTL, there is a possibility that the oscillation erroneously counts because X1A has noise with the change of P48/VREGCTL. Keep as much distance as possible between both wirings and insert the ground pattern between them in order to avoid this possibility.



Handling when Using Debug Pins

When debug pins(TDO/TMS/TDI/TCK/TRSTX or SWO/SWDIO/SWCLK) are set to GPIO or other peripheral functions, only set them as output, do not set them as input.

8. Block Diagram



*: For the S6E2H44E0A and S6E2H46E0A, ETM is not available.

Current Explanation Diagram

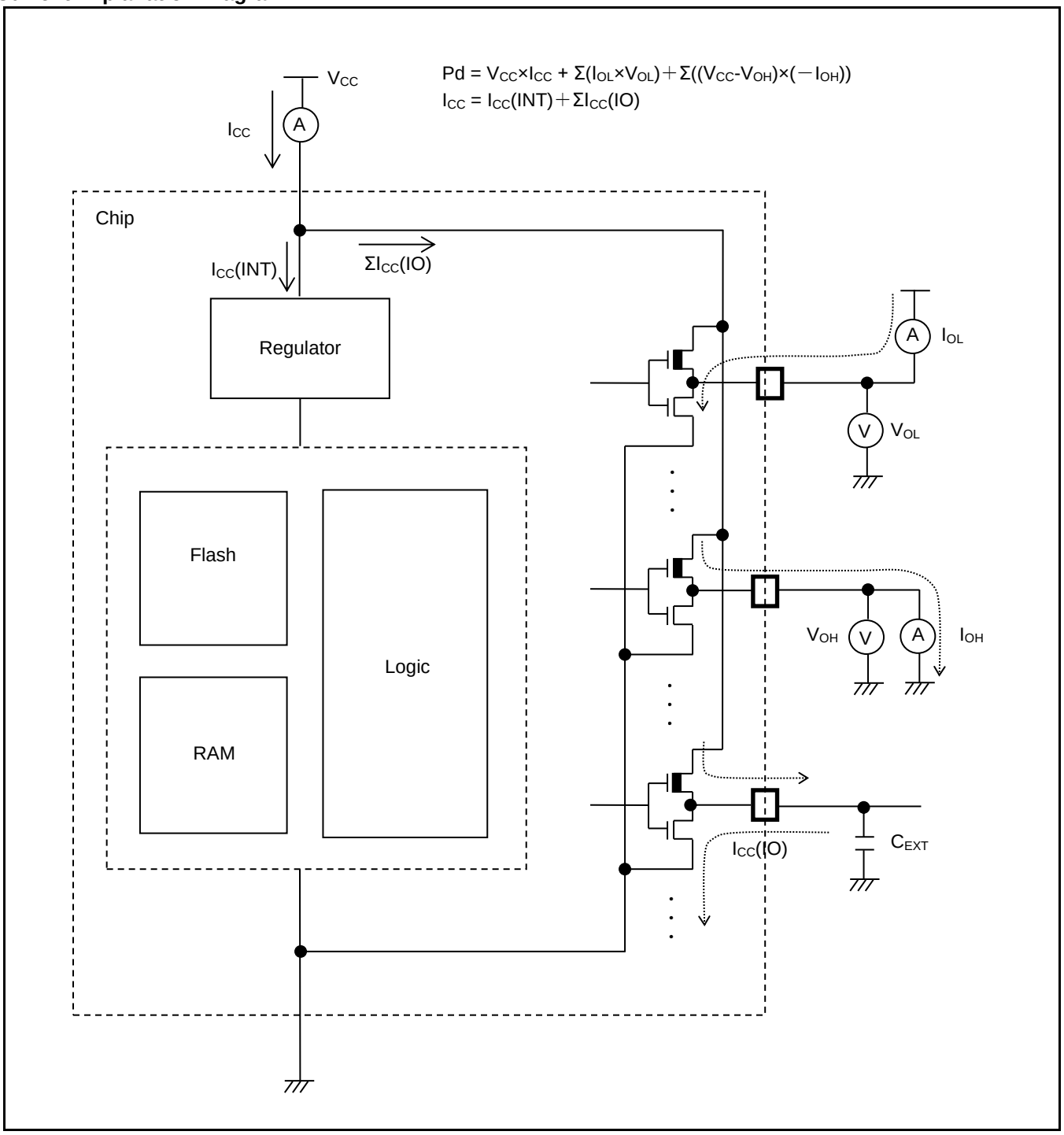


Table 12-6 Typical and Maximum Current Consumption in Sleep Operation(PLL), when PCLK0 = PCLK1 = PCLK2 = HCLK

Parameter	Symbol	Pin Name	Conditions	Frequency*5	Value		Unit	Remarks
					Typ*1	Max*2		
Power supply current	I_{CCS}	VCC	Sleep operation *6 (PLL)	72 MHz	23	43	mA	*3 When all peripheral clocks are ON
				60 MHz	19	39		
				48 MHz	16	36		
				36 MHz	12	32		
				24 MHz	8.5	29		
				12 MHz	5.1	25		
				8 MHz	3.9	24		
				4 MHz	2.7	23		
				72 MHz	8.8	29	mA	*3 When all peripheral clocks are OFF
				60 MHz	7.6	28		
				48 MHz	6.3	27		
				36 MHz	5.1	25		
				24 MHz	3.9	24		
				12 MHz	2.7	23		
				8 MHz	2.3	23		
				4 MHz	1.9	22		

*1: T_A=+25°C, V_{CC}=3.3 V

*2: T_J=+125°C, V_{CC}=5.5 V

*3: When all ports are fixed.

*4: Frequency is a value of HCLK. PCLK0=PCLK1=PCLK2=HCLK/2

*5: Frequency is a value of HCLK. PCLK0=PCLK1=PCLK2=HCLK

*6: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

Separate Bus Access Synchronous SRAM Mode

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit
				Min	Max	
Address delay time	t_{AV}	MCLK, MAD[24:0]	$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
MCSX delay time	t_{CSL}	MCLK, MCSX[7:0]	$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
	t_{CSH}		$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
MOEX delay time	t_{REL}	MCLK, MOEX	$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
	t_{REH}		$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
Data set up →MCLK↑ time	t_{DS}	MCLK, MADATA[15:0]	$V_{CC} \geq 4.5$ V	19	-	ns
			$V_{CC} < 4.5$ V	37		
MCLK↑→ Data hold time	t_{DH}	MCLK, MADATA[15:0]	$V_{CC} \geq 4.5$ V	0	-	ns
			$V_{CC} < 4.5$ V			
MWEX delay time	t_{WEL}	MCLK, MWEX	$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
	t_{WEH}		$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
MDQM[1:0] delay time	t_{DQML}	MCLK, MDQM[1:0]	$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
	t_{DQMH}		$V_{CC} \geq 4.5$ V	1	9	ns
			$V_{CC} < 4.5$ V		12	
MCLK↑→ Data output time	t_{ODS}	MCLK, MADATA[15:0]	$V_{CC} \geq 4.5$ V	MCLK+1	MCLK+18	ns
			$V_{CC} < 4.5$ V		MCLK+24	
MCLK↑→ Data hold time	t_{OD}	MCLK, MADATA[15:0]	$V_{CC} \geq 4.5$ V	1	18	ns
			$V_{CC} < 4.5$ V		24	

Note:

- *When the external load capacitance C_L = 30 pF*

NAND Flash Mode

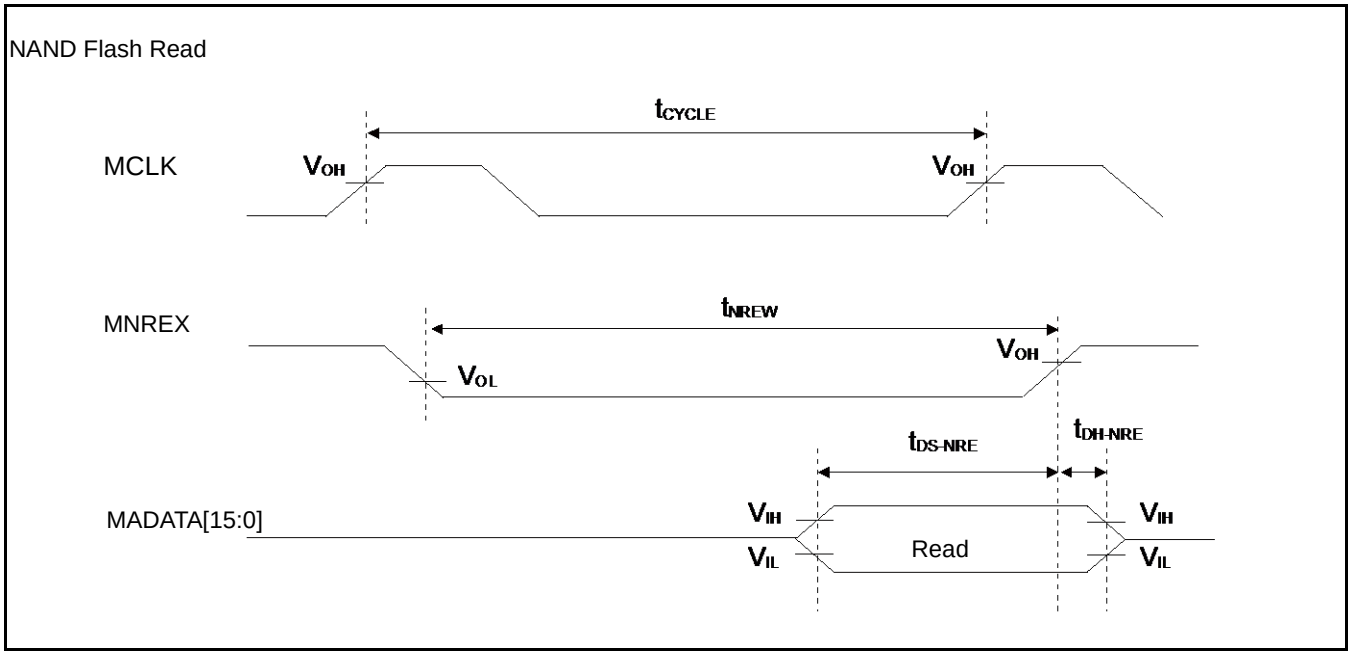
(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit
				Min	Max	
MNREX Min pulse width	t_{NREW}	MNREX	$V_{CC} \geq 4.5$ V	MCLK×n-3	-	ns
			$V_{CC} < 4.5$ V			
Data set up →MNREX↑ time	t_{DS-NRE}	MNREX, MADATA[15:0]	$V_{CC} \geq 4.5$ V	20	-	ns
			$V_{CC} < 4.5$ V	38	-	
MNREX↑→ Data hold time	t_{DH-NRE}	MNREX, MADATA[15:0]	$V_{CC} \geq 4.5$ V	0	-	ns
			$V_{CC} < 4.5$ V			
MNALE↑→ MNWEX delay time	$t_{ALEH-NWEL}$	MNALE, MNWEX	$V_{CC} \geq 4.5$ V	MCLK×m-9	MCLK×m+9	ns
			$V_{CC} < 4.5$ V	MCLK×m-12	MCLK×m+12	
MNALE↓→ MNWEX delay time	$t_{ALEL-NWEL}$	MNALE, MNWEX	$V_{CC} \geq 4.5$ V	MCLK×m-9	MCLK×m+9	ns
			$V_{CC} < 4.5$ V	MCLK×m-12	MCLK×m+12	
MNCLE↑→ MNWEX delay time	$t_{CLEH-NWEL}$	MNCLE, MNWEX	$V_{CC} \geq 4.5$ V	MCLK×m-9	MCLK×m+9	ns
			$V_{CC} < 4.5$ V	MCLK×m-12	MCLK×m+12	
MNWEX↑→ MNCLE delay time	$t_{NWEH-CLEL}$	MNCLE, MNWEX	$V_{CC} \geq 4.5$ V	0	MCLK×m+9	ns
			$V_{CC} < 4.5$ V		MCLK×m+12	
MNWEX Min pulse width	t_{NWEW}	MNWEX	$V_{CC} \geq 4.5$ V	MCLK×n-3	-	ns
			$V_{CC} < 4.5$ V			
MNWEX↓→ Data output time	$t_{NWEL-DV}$	MNWEX, MADATA[15:0]	$V_{CC} \geq 4.5$ V	- 9	+ 9	ns
			$V_{CC} < 4.5$ V	-12	+12	
MNWEX↑→ Data hold time	$t_{NWEH-DX}$	MNWEX, MADATA[15:0]	$V_{CC} \geq 4.5$ V	0	MCLK×m+9	ns
			$V_{CC} < 4.5$ V		MCLK×m+12	

Note:

- *When the external load capacitance C_L = 30 pF (m=0 to 15, n=1 to 16)*

NAND Flash Read



Synchronous Serial (SPI = 0, SCINV = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↑→SOT delay time	t_{SHOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN→SCK↓ setup time	t_{IVSLI}	SCKx, SINx		50	-	30	-	ns
SCK↓→SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2tC_{YCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↑→SOT delay time	t_{SHOVE}	SCKx, SOTx		-	50	-	30	ns
SIN→SCK↓ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	ns
SCK↓→SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	ns

Notes:

- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time.*
  About the APB bus number which multi-function serial is connected to, see 8. Block Diagram in this data sheet.
- *These characteristics only guarantee the same relocate port number.*
  For example, the combination of SCLKx_0 and SOTx_1 is not guaranteed.
- *When the external load capacitance C_L = 30 pF.*

When Using Synchronous Serial Chip Select (SPI = 1, SCINV = 1, MS=0, CSLVL=0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↑→SCK↑setup time	t_{CSSI}	Internal shift clock operation	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK↓→SCS↓ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	ns
SCS↑→SCK↑setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCK↓→SCS↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCS↑→SOT delay time	t_{DSE}		-	40	-	40	ns
SCS↓→SOT delay time	t_{DEE}		0	-	0	-	ns

(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time.*
  About the APB bus number which multi-function serial is connected to, see 8. Block Diagram in this data sheet.
- *About CSSU, CSHD, CSDS, serial chip select timing operating clock, see FM4 Family Peripheral Manual Main part(MN709-00001).*
- *When the external load capacitance C_L = 30 pF.*

When Using High-speed Synchronous Serial Chip Select (SPI = 1, SCINV = 1, MS=0, CSLVL=1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↑setup time	t_{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↓→SCS↑ hold time	t_{CSHI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t_{CSDI}		(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	ns
SCS↓→SCK↑setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCK↓→SCS↑ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCS↓→SOT delay time	t_{DSE}		-	25	-	25	ns
SCS↑→SOT delay time	t_{DEE}		0	-	0	-	ns

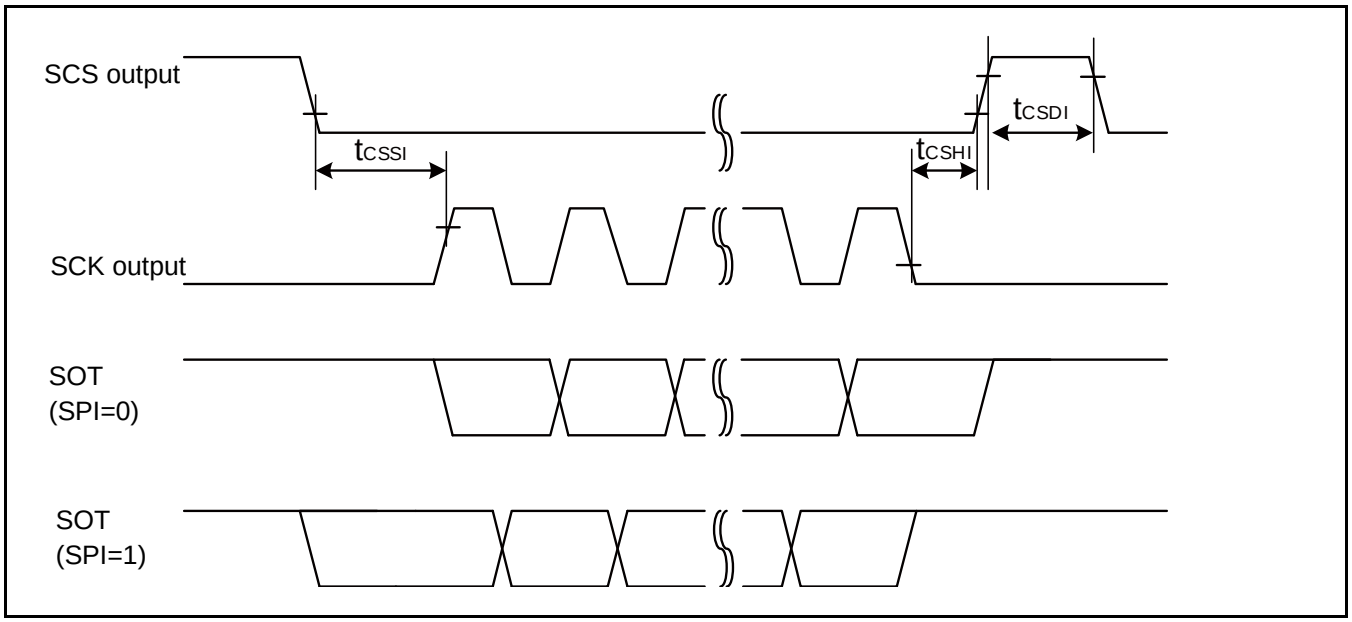
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

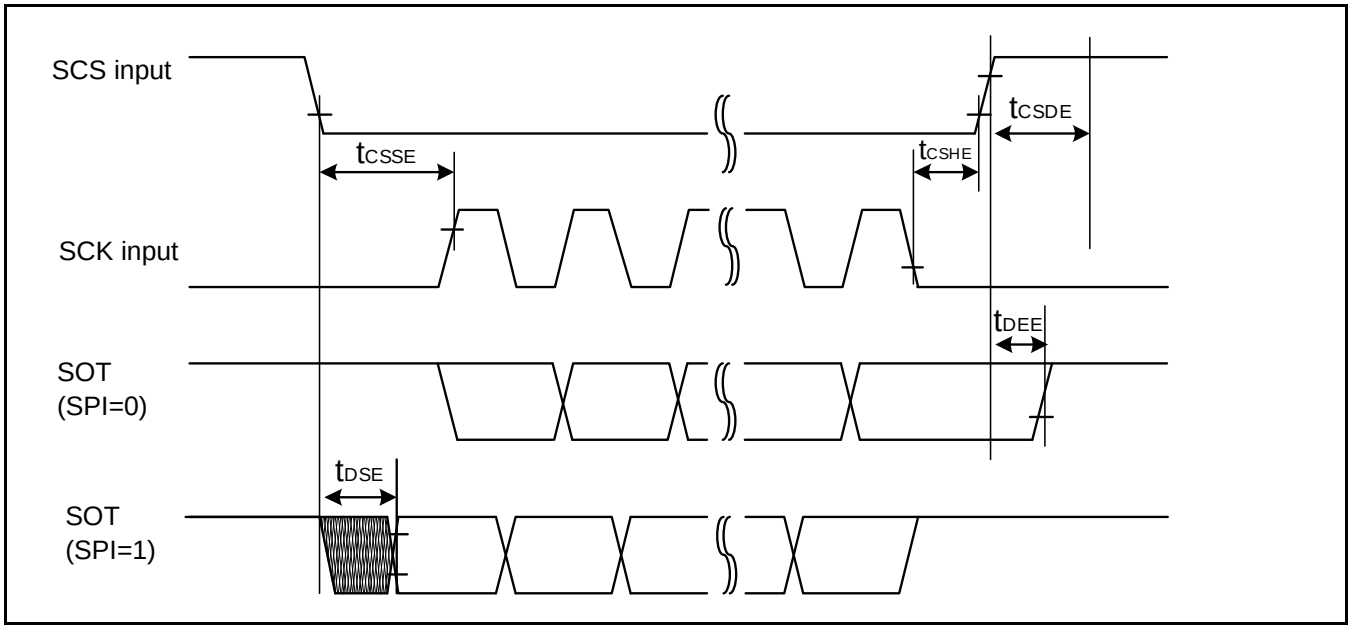
(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time.*
  About the APB bus number which multi-function serial is connected to, see 8. Block Diagram in this data sheet.
- *About CSSU, CSHD, CSDS, serial chip select timing operating clock, see FM4 Family Peripheral Manual Main part(MN709-00001).*
- *When the external load capacitance C_L = 30 pF.*


SCS output
tCSSI
tCSDI
tCSHI
SCK output
SOT
(SPI=0)
SOT
(SPI=1)


SCS input
tCSDE
tCSSE
tCSHE
SCK input
tDEE
SOT
(SPI=0)
tDSE
SOT
(SPI=1)

12.4.14 I^2C Timing

Standard-mode, Fast-mode

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	Standard-mode		Fast-mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	f_{SCL}	C_L = 30 pF, R = (Vp/I_{OL})*1	0	100	0	400	kHz	
(Repeated) Start condition hold time SDA ↓ → SCL ↓	t_{HDSTA}		4.0	-	0.6	-	µs	
SCL clock L width	t_{LOW}		4.7	-	1.3	-	µs	
SCL clock H width	t_{HIGH}		4.0	-	0.6	-	µs	
(Repeated) Start condition setup time SCL ↑ → SDA ↓	t_{SUSTA}		4.7	-	0.6	-	µs	
Data hold time SCL ↓ → SDA ↓ ↑	t_{HDDAT}		0	3.45*2	0	0.9*3	µs	
Data setup time SDA ↓ ↑ → SCL ↑	t_{SUDAT}		250	-	100	-	ns	
STOP condition setup time SCL ↑ → SDA ↑	t_{SUSTO}		4.0	-	0.6	-	µs	
Bus free time between Stop condition and Start condition	t_{BUF}		4.7	-	1.3	-	µs	
Noise filter	t_{SP}	2 MHz ≤ t_{CYCP}<40 MHz	$2t_{CYCP}$*4	-	$2t_{CYCP}$*4	-	ns	*5
		40 MHz ≤ t_{CYCP}<60 MHz	$4t_{CYCP}$*4	-	$4t_{CYCP}$*4	-	ns	
		60 MHz ≤ t_{CYCP}<80 MHz	$6t_{CYCP}$*4	-	$6t_{CYCP}$*4	-	ns	
		80 MHz ≤ t_{CYCP}<100 MHz	$8t_{CYCP}$*4	-	$8t_{CYCP}$*4	-	ns	
		100 MHz ≤ t_{CYCP}<120 MHz	$10t_{CYCP}$*4	-	$10t_{CYCP}$*4	-	ns	
		120 MHz ≤ t_{CYCP}<140 MHz	$12t_{CYCP}$*4	-	$12t_{CYCP}$*4	-	ns	
		140 MHz ≤ t_{CYCP}<160 MHz	$14t_{CYCP}$*4	-	$14t_{CYCP}$*4	-	ns	
		160 MHz ≤ t_{CYCP}<180 MHz	$16t_{CYCP}$*4	-	$16t_{CYCP}$*4	-	ns	

1: R and C_L represent the pull-up resistance and load capacitance of the SCL and SDA lines, respectively. V_p indicates the power supply voltage of the pull-up resistance and I_{OL} indicates V_{OL} guaranteed current.

2: The maximum t_{HDDAT} must not extend beyond the low period (t_{LOW}) of the device's SCL signal.

3: Fast-mode I^2C bus device can be used on a Standard-mode I^2C bus system as long as the device satisfies the requirement of t_{SUDAT} ≥ 250 ns.

4: t_{CYCP} is the APB bus clock cycle time. For more information about the APB bus number to which the I^2C is connected, see 8.Block Diagram in this data sheet.
When using Standard-mode, the peripheral bus clock must be set more than 2 MHz.
When using Fast-mode, the peripheral bus clock must be set more than 8 MHz.

5: The noise filter time can be changed by register settings. Change the number of the noise filter steps according to the APB bus clock frequency.

12.10.2 Recovery Cause: Reset

The time from reset release to the program operation start is shown.

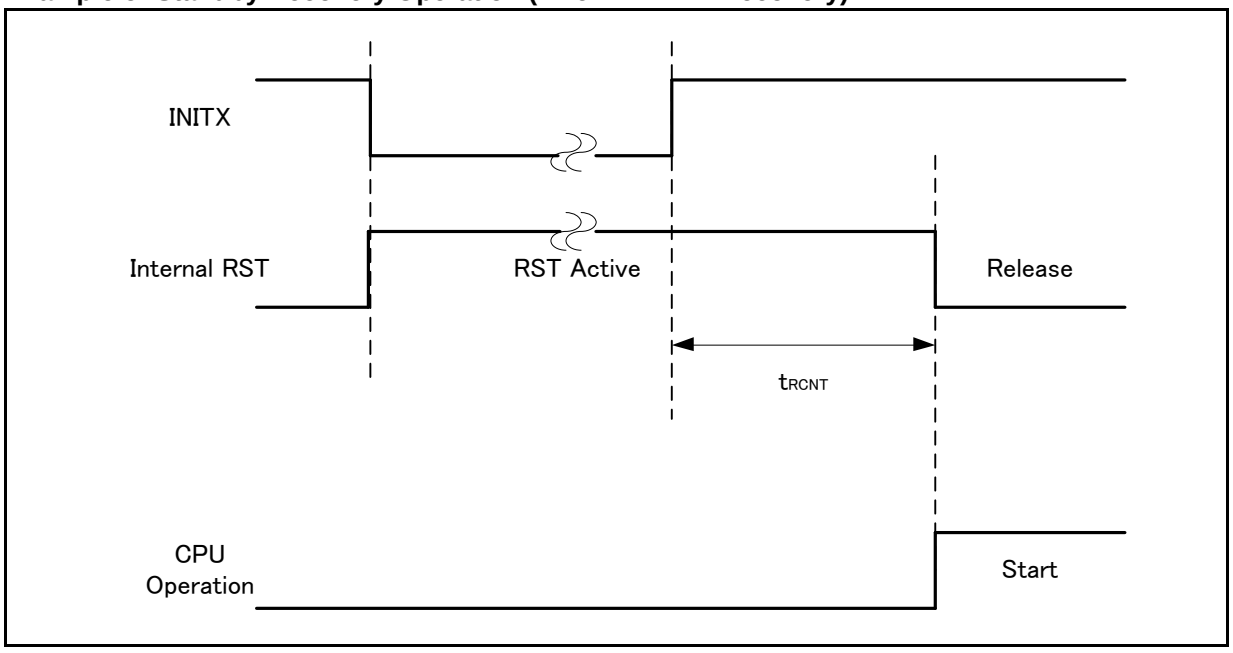
Recovery Count Time

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
Sleep mode	t_{RCNT}	155	266	µs	
High-speed CR timer mode Main timer mode PLL timer mode		155	266	µs	
Low-speed CR timer mode		315	567	µs	
Sub timer mode		315	567	µs	
RTC mode Stop mode		315	567	µs	
Deep standby RTC mode with RAM retention		336	667	µs	without RAM retention
Deep standby stop mode with RAM retention				µs	with RAM retention

*: The maximum value depends on the built-in CR accuracy.

Example of Standby Recovery Operation (when in INITX Recovery)

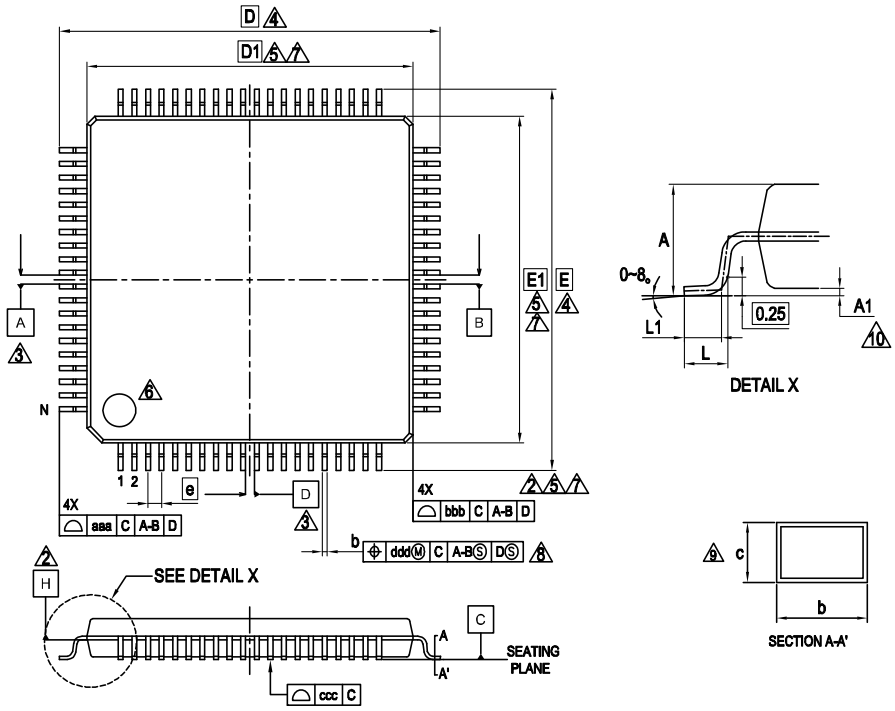


13. Ordering Information

Part Number	Package
S6E2H46G0A GV20000	Plastic LQFP (0.5-mm pitch), 120 pin (LQM120)
S6E2H44G0A GV20000	
S6E2H46F0A GV20000	Plastic LQFP (0.5-mm pitch), 100 pin (LQI100)
S6E2H44F0A GV20000	
S6E2H46E0A GV20000	Plastic LQFP (0.5-mm pitch), 80 pin (LQH080)
S6E2H44E0A GV20000	
S6E2H46G0A GB30000	Plastic FBGA (0.5-mm pitch), 121 pin (FDI121)
S6E2H44G0A GB30000	

Package Type	Package Code
LQFP 80	LQH080

LQH080 , 80 Lead Plastic Low Profile Quad Flat Package



PACKAGE	LQH080		
SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.05	—	0.15
b	0.15	0.20	0.25
c	0.09	—	0.20
D	14.00 BSC.		
D1	12.00 BSC.		
e	0.50 BSC		
E	14.00 BSC.		
E1	12.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
aaa	—	—	0.20
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.08
N	80		

NOTES

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm)
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

Rev. A